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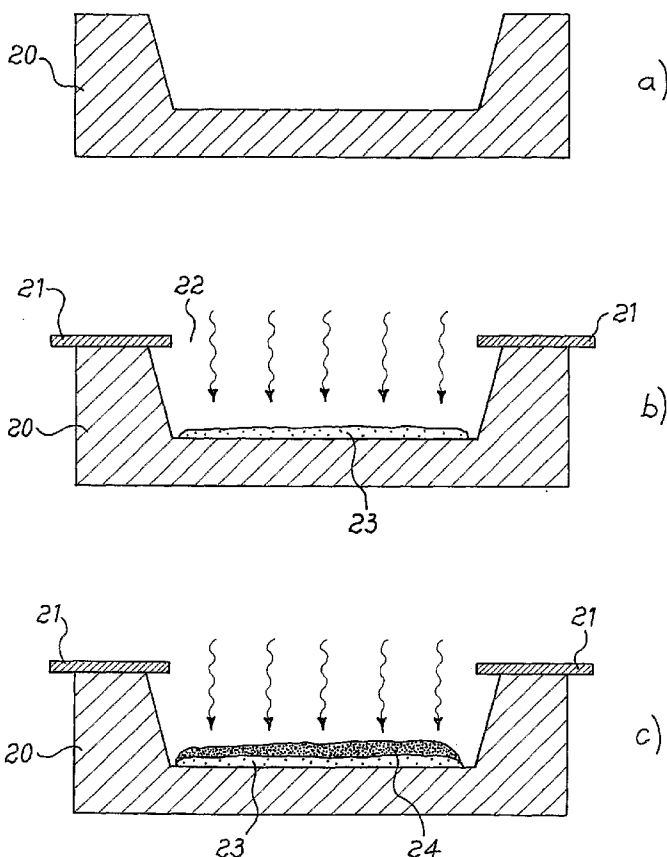
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(54) Title: PROCESS FOR MANUFACTURING MICROMECHANICAL DEVICES CONTAINING A GETTER MATERIAL AND DEVICES SO MANUFACTURED



(57) Abstract: A process for manufacturing micromechanical devices is described, said devices being formed by joining two parts together by direct bonding, one of the parts (12) being made of silicon and the other one being made of a material chosen between silicon and a semiconductor ceramic or oxidic material, such that the joint between the two parts forms a cavity (14) containing the functional elements of the device (11), possible auxiliary elements and a getter material deposit (13).



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